



BSI Standards Publication

# Mechanical standardization of semiconductor devices

Part 6-20: General rules for the preparation  
of outline drawings of surface mounted  
semiconductor device packages —  
Measuring methods for package  
dimensions of small outline J-lead  
packages (SOJ)

**National foreword**

This British Standard is the UK implementation of EN 60191-6-20:2010. It is identical to IEC 60191-6-20:2010.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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EUROPEAN STANDARD  
NORME EUROPÉENNE  
EUROPÄISCHE NORM

# EN 60191-6-20

October 2010

ICS 31.080.01

English version

**Mechanical standardization of semiconductor devices -  
Part 6-20: General rules for the preparation of outline drawings of surface  
mounted semiconductor device packages -  
Measuring methods for package dimensions of small outline J-lead  
packages (SOJ)  
(IEC 60191-6-20:2010)**

Normalisation mécanique des dispositifs à  
semiconducteurs -  
Part 6-20: Règles générales pour la  
préparation des dessins d'encombrement  
des boîtiers pour dispositifs à  
semiconducteurs pour montage en  
surface -  
Méthodes de mesure pour les dimensions  
des boîtiers à sortie en J (SOJ) de faible  
encombrement  
(CEI 60191-6-20:2010)

Mechanische Normung von  
Halbleiterbauelementen -  
Teil 6-20: Allgemeine Regeln für die  
Erstellung von Gehäusezeichnungen von  
SMD-Halbleitergehäusen -  
Messverfahren für Gehäusemaße von  
kleinen Gehäusen mit J-förmigen  
Anschlüssen (SOJ)  
(IEC 60191-6-20:2010)

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

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## Foreword

The text of document 47D/771/FDIS, future edition 1 of IEC 60191-6-20, prepared by SC 47D, Mechanical standardization for semiconductor devices, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-6-20 on 2010-10-01.

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The following dates were fixed:

- |                                                                                                                                          |       |            |
|------------------------------------------------------------------------------------------------------------------------------------------|-------|------------|
| – latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement | (dop) | 2011-07-01 |
| – latest date by which the national standards conflicting with the EN have to be withdrawn                                               | (dow) | 2013-10-01 |

Annex ZA has been added by CENELEC.

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## Endorsement notice

The text of the International Standard IEC 60191-6-20:2010 was approved by CENELEC as a European Standard without any modification.

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## **Annex ZA** (normative)

### **Normative references to international publications with their corresponding European publications**

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

| <u>Publication</u> | <u>Year</u> | <u>Title</u>                                                                                                                                                            | <u>EN/HD</u> | <u>Year</u> |
|--------------------|-------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------|-------------|
| IEC 60191-4        | -           | Mechanical standardization of semiconductor devices -<br>Part 4: Coding system and classification into forms of package outlines for semiconductor device packages      | EN 60191-4   | -           |
| IEC 60191-6        | -           | Mechanical standardization of semiconductor devices -<br>Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages | EN 60191-6   | -           |